

Title (en)  
COPPER ALLOY SHEET

Title (de)  
KUPFERLEGIERUNGSBLECH

Title (fr)  
FEUILLE EN ALLIAGE DE CUIVRE

Publication  
**EP 2221391 B1 20140430 (EN)**

Application  
**EP 08847798 A 20081105**

Priority  
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Abstract (en)  
[origin: EP2221391A1] A copper alloy sheet material which has a tensile strength of 730-820 MPa and contains at least nickel (Ni) and silicon (Si) , with the remainder being copper (Cu) and inevitable impurities. When the sheet material has a shape capable of 180° tight bending and the width and thickness of this sheet material are expressed by W (unit: mm) and T (unit: mm) respectively, then the product of W and T is 0.16 or less. Preferably, the sheet material is constituted of an alloy containing nickel at 1.8-3.3 mass%, silicon at 0.4 mass%, and chromium (Cr) at 0.01-0.5 mass%, with the remainder being copper and inevitable impurities. The sheet material may further contain one or more of: at least one member selected among tin (Sn), magnesium (Mg), silver (Ag), manganese (Mn), titanium (Ti), iron (Fe), and phosphorus (P) in a total amount of 0.01-1 mass%; zinc (Zn) at 0.01-10 mass%, cobalt (Co) at and 0.01-1.5 mass%.

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